

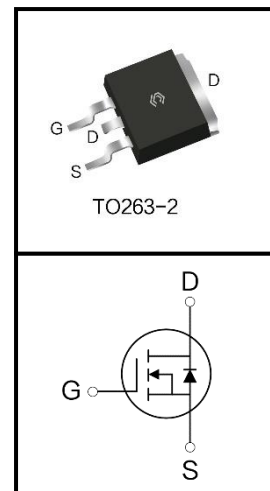
# 800V Super-Junction Power MOSFET

## FEATURES

- Very low FOM  $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- RoHS compliant
- Fast switching
- Integrate fast recovery diode

## APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



## Device Marking and Package Information

Device	Package	Marking
CLB80R200MF	TO263-2	CLB80R200MF

## Absolute Maximum Ratings at $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS} = 0V$ )	$V_{DSS}$	800	V
Continuous Drain Current	$I_D$	24	A
Continuous Drain Current $T_c = 100^\circ\text{C}$		14	
Pulsed Drain Current (note1)	$I_{DM}$	72	A
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Single Pulse Avalanche Energy (note2)	$E_{AS}$	172	mJ
Repetitive Avalanche Energy (note1)	$E_{AR}$	0.68	mJ
Power Dissipation	$P_D$	379	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	$-55 \sim +150$	$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-Case	$R_{\theta JC}$	0.33	$^\circ\text{C/W}$
Thermal Resistance, Junction-Ambient	$R_{\theta JA}$	62.5	

**Electrical Characteristics  $T_J = 25^\circ\text{C}$  unless otherwise specified**

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain–Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250uA	800	--	--	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 800V, V <sub>GS</sub> = 0V	--	--	10	uA
Gate–Source Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 30V	--	--	± 100	nA
Gate–Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250uA	3.0	4.0	5.0	V
Drain–Source On–Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 12A	--	0.17	0.2	Ω
Gate resistance	R <sub>G</sub>	f = 1.0MHz open drian	--	1.3	--	Ω
Dynamic						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 100V, f = 250kHz	--	2858	--	pF
Output Capacitance	C <sub>oss</sub>		--	75	--	
Reverse Transfer Capacitance	C <sub>rss</sub>		--	1.3	--	
Effective Output Capacitance (Energy Related)	C <sub>o(er)</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0~400V	--	32	--	pF
Effective Output Capacitance (Time Related)	C <sub>o(tr)</sub>		--	343	--	pF
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> = 640V, I <sub>D</sub> = 12A, V <sub>GS</sub> = 0~10V	--	60	--	nC
Gate–Source Charge	Q <sub>gs</sub>		--	15	--	
Gate–Drain Charge	Q <sub>gd</sub>		--	24	--	
Gate Plateau Voltage	V <sub>pl</sub>		--	5.9	--	V
Turn–on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 400V, I <sub>D</sub> = 12A, R <sub>G</sub> = 25Ω	--	63	--	ns
Turn–on Rise Time	t <sub>r</sub>		--	31	--	
Turn–off Delay Time	t <sub>d(off)</sub>		--	228	--	
Turn–off Fall Time	t <sub>f</sub>		--	40	--	
Body Diode Characteristics						
Continuous Body Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25°C	--	--	24	A
Pulsed Diode Forward Current	I <sub>SM</sub>		--	--	72	
Body Diode Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25°C, I <sub>SD</sub> = 12A, V <sub>GS</sub> = 0V	--	0.91	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> = 400V, I <sub>F</sub> = 12A, di <sub>F</sub> /dt = 100A/μ s	--	180	--	ns
Reverse Recovery Charge	Q <sub>rr</sub>		--	0.97	--	μ C
Peak Reverse Recovery Current	I <sub>rrm</sub>		--	9	--	A

**Notes**

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $I_{AS} = 6A, V_{DD} = 50V, R_G = 25\Omega, L = 10\text{mH}$ , Starting  $T_J = 25^\circ\text{C}$
3. Pulse Test: Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 1\%$

Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 1. Typ.Output Characteristics

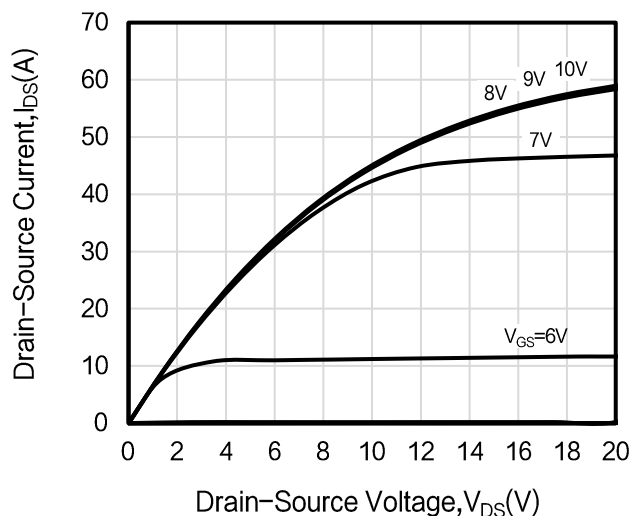


Figure 2. Transfer Characteristics

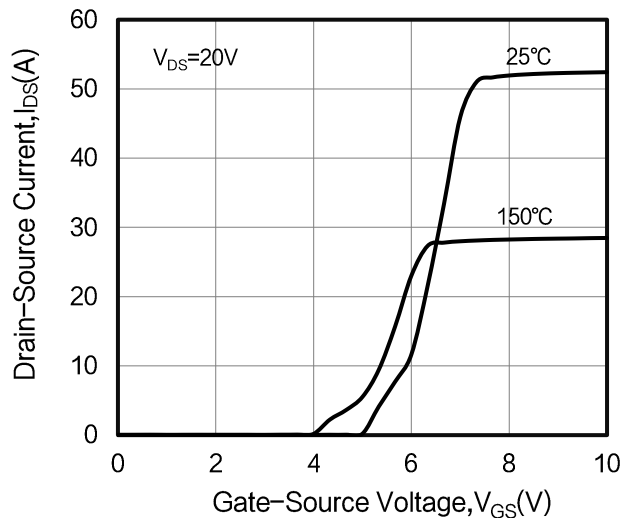


Fig.3 On-Resistance vs.Drain Current

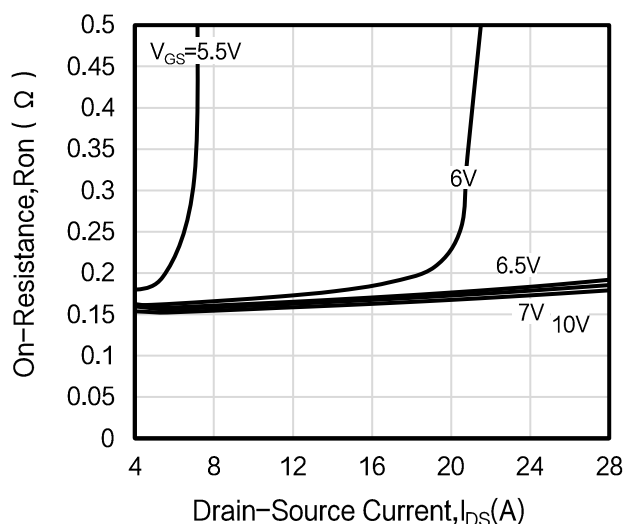


Fig.4 On-Resistance vs. Temperature

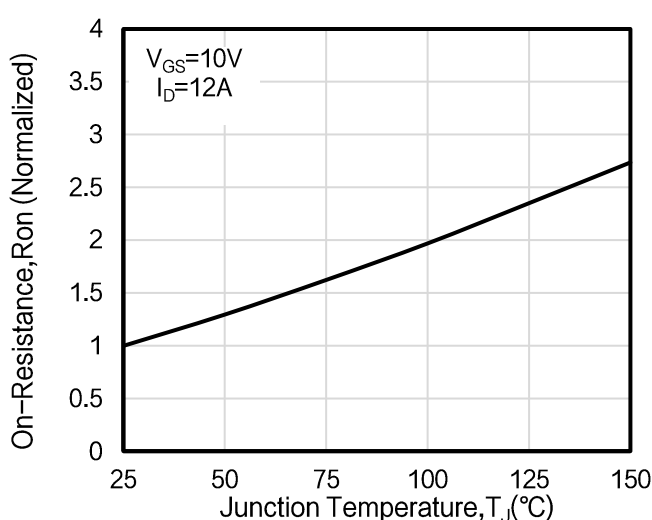


Figure 5. Body Diode Forward Voltage

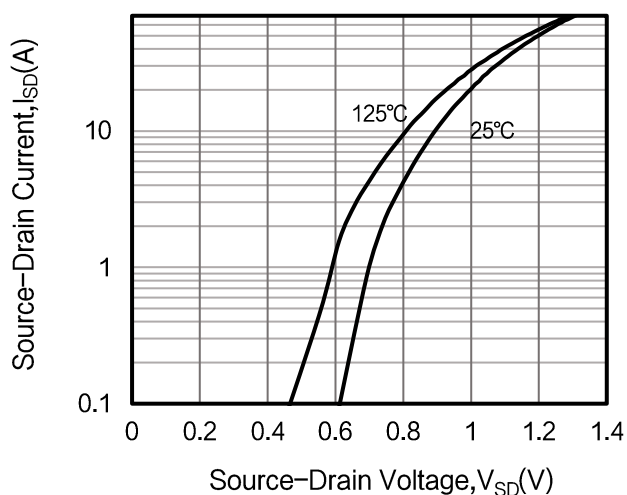
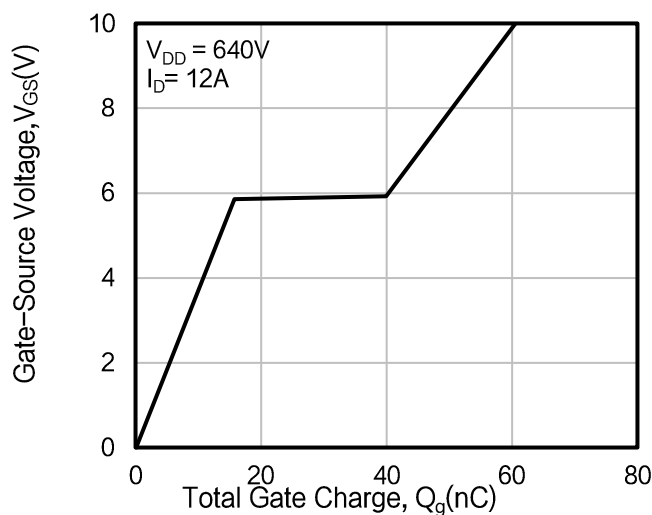


Figure 6. Gate Charge



Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 7. Breakdown Voltage vs. Temperature

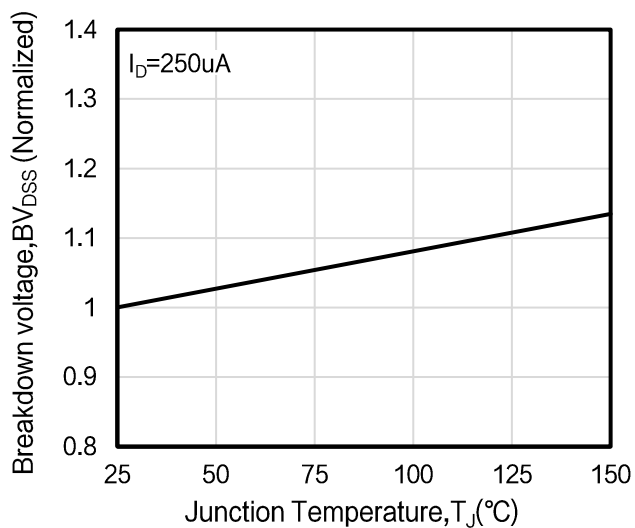


Fig.8 Capacitances

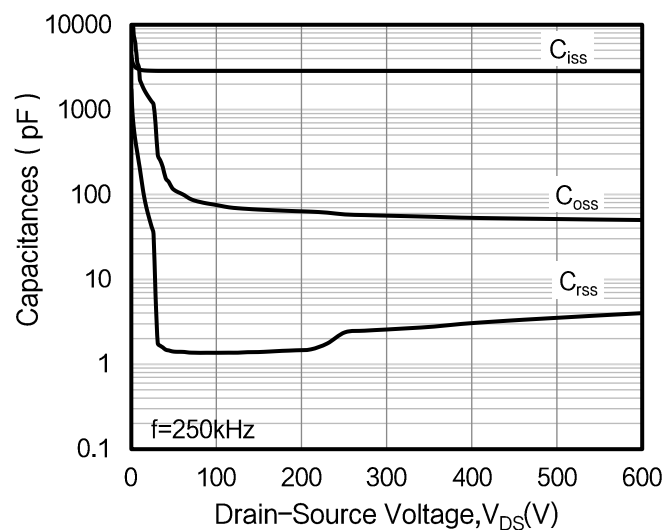


Fig.9 Coss Stored Energy

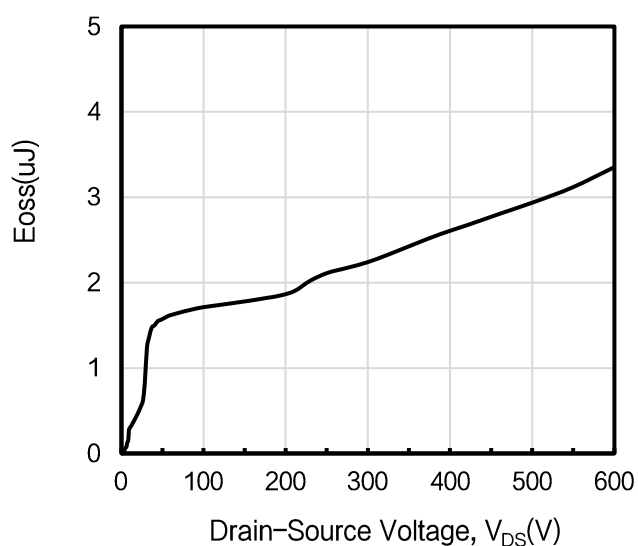


Figure10. Power Dissipation

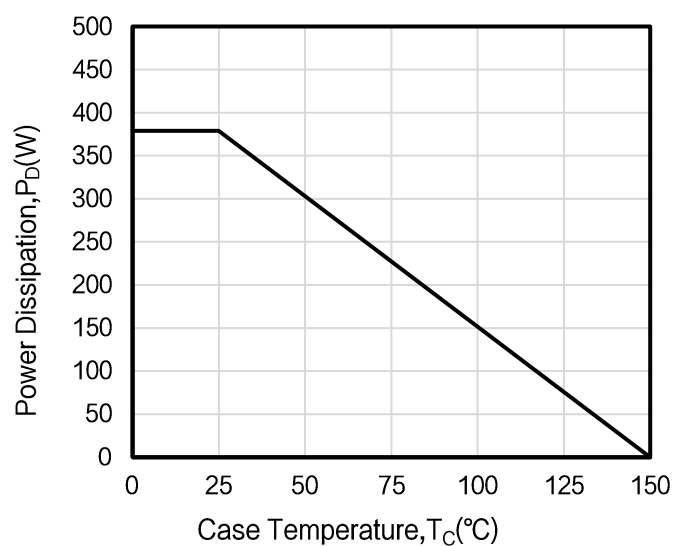


Figure 11. Transient Thermal Impedance

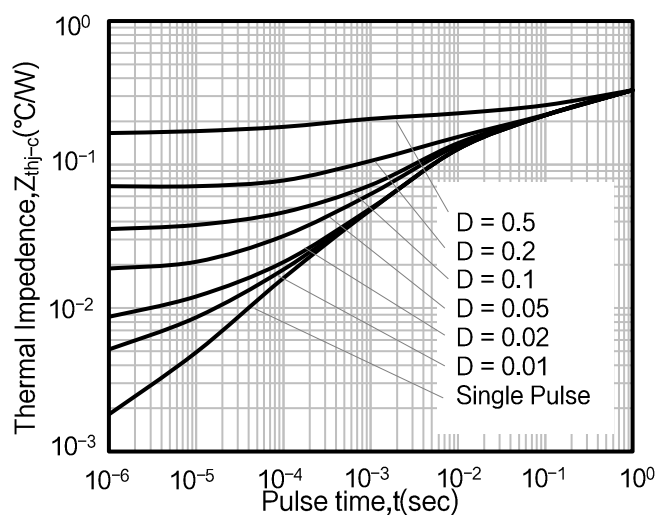


Figure 12. Safe Operation Area

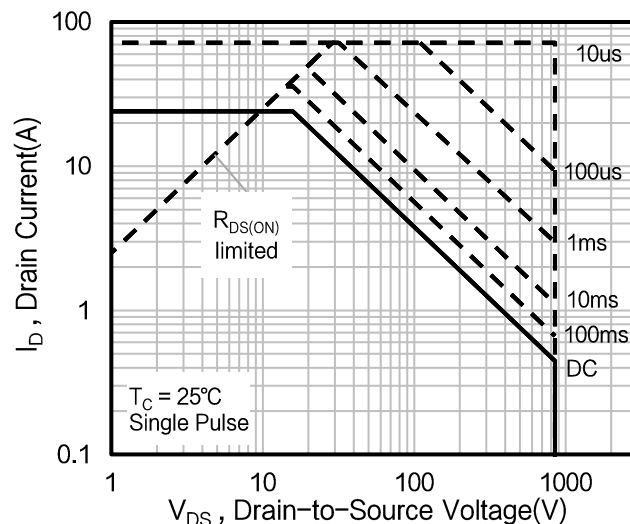


Figure A: Gate Charge Test Circuit and Waveform

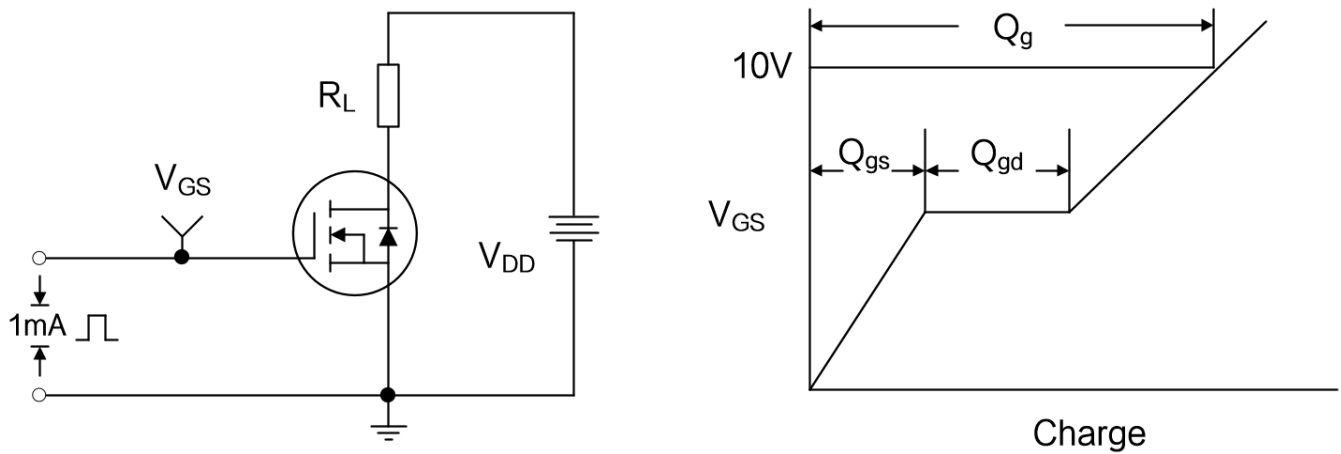


Figure B: Resistive Switching Test Circuit and Waveform

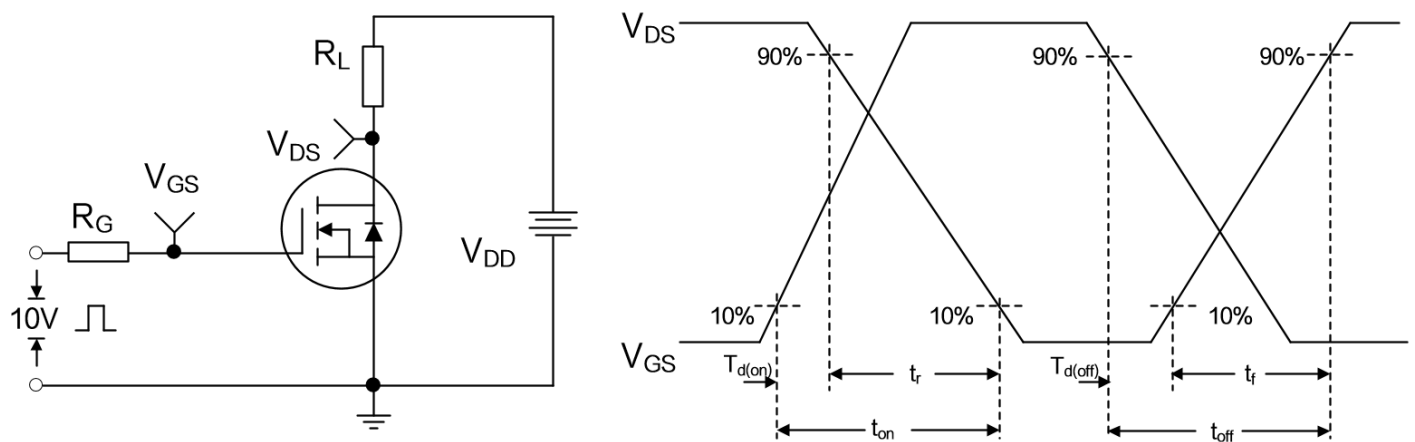
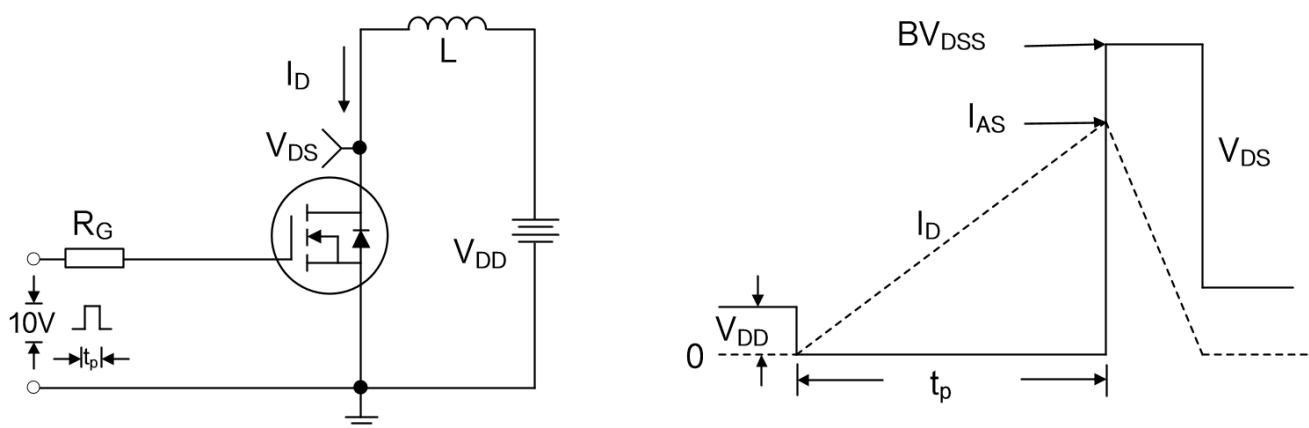
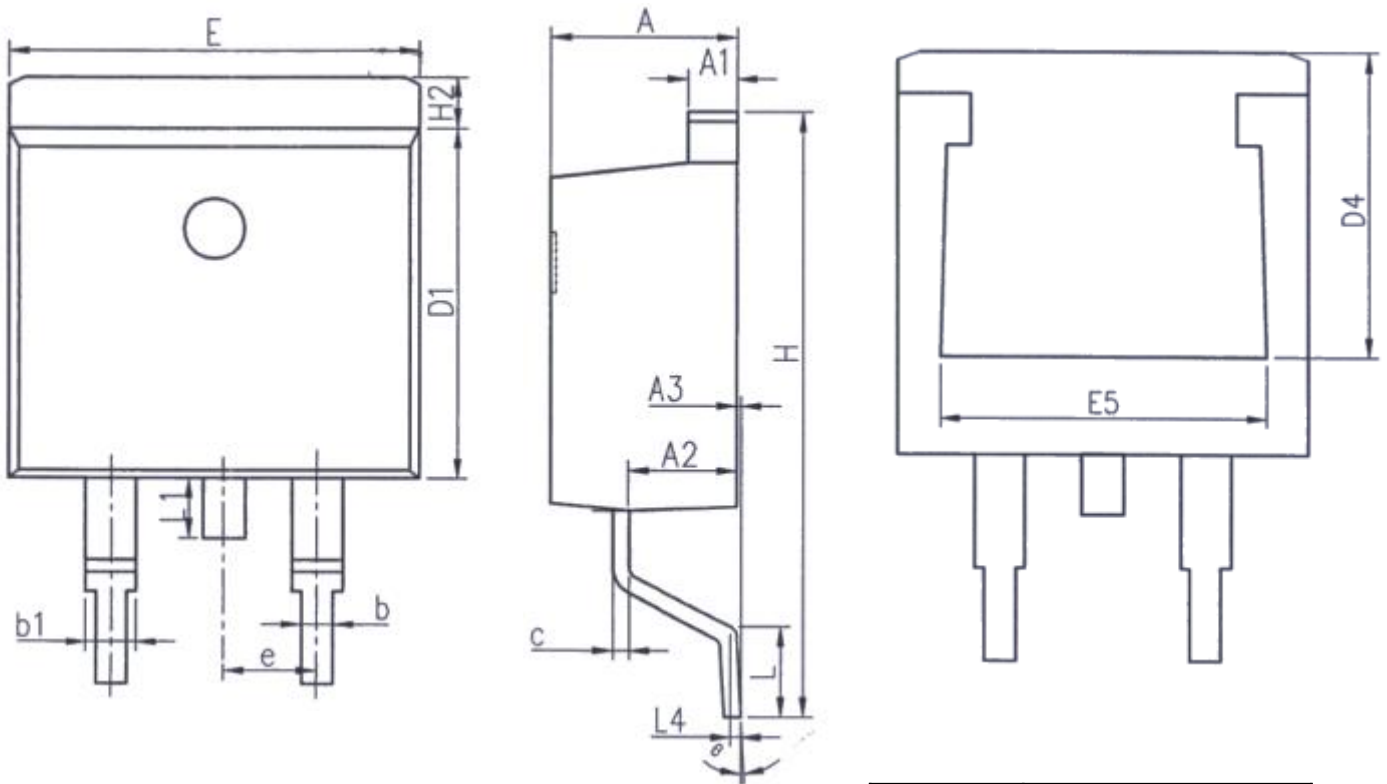


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



# TO263-2



SYMBOLS	MILLIMETERS	
	MIN	MAX
A	4.37	4.77
A1	1.22	1.40
A2	2.49	2.89
A3	0.00	0.25
b	0.7	0.96
b1	1.17	1.47
c	0.30	0.53
D1	8.50	8.90
D4	6.60	–
E	9.86	10.36
E5	7.06	–
e	2.54 BSC	
H	14.70	15.50
H2	1.07	1.47
L	2.00	2.60
L4	025 BSC	
Φ	0°	9°

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